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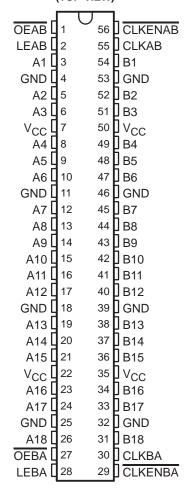
- **Members of the Texas Instruments** Widebus™ Family
- B-Port Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- **UBT** ™ (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs.

SN54ABT162601...WD PACKAGE SN74ABT162601...DGG OR DL PACKAGE (TOP VIEW)



For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output-enable OEAB is active-low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B but uses \overline{OEBA} , LEBA, CLKBA, and $\overline{CLKENBA}$.

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent $25-\Omega$ series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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SN54ABT162601, SN74ABT162601 18-BIT UNIVERSAL BUS TRANSCEIVERS **WITH 3-STATE OUTPUTS**

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description (continued)

The SN54ABT162601 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162601 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE[†]

	II	NPUTS			OUTPUT
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Х	Х	Х	Z
Х	L	Н	X	L	L
Х	L	Н	X	Н	Н
Н	L	L	X	Χ	в ₀ ‡
Н	L	L	X	Χ	В ₀ ‡ В ₀ ‡
L	L	L	\uparrow	L	L
L	L	L	\uparrow	Н	Н
L	L	L	L	Χ	в ₀ ‡
L	L	L	Н	Χ	В ₀ ‡ В ₀ §

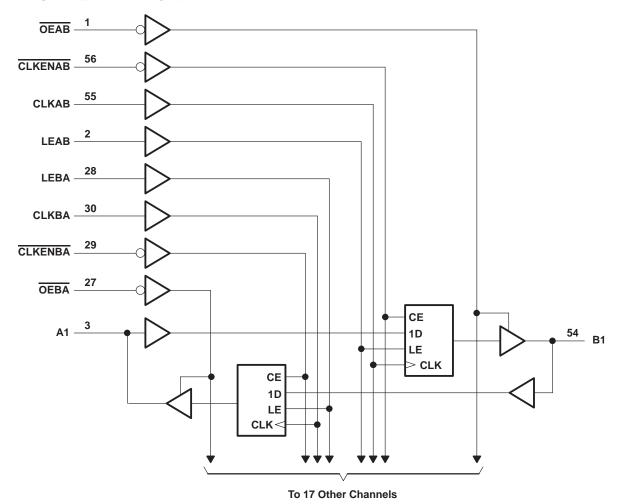
[†] A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CLKBA, and CLKENBA.



[‡] Output level before the indicated steady-state input conditions were established

[§] Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	\dots -0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT162601 (A port)	96 mA
SN74ABT162601 (A port)	128 mA
B port	30 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	
Storage temperature range, T _{stq}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



SN54ABT162601, SN74ABT162601 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

			SN54ABT	162601	SN74ABT162601		UNIT	
			MIN	MAX	UNIT			
VCC	Supply voltage		4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V	
V_{IL}	Low-level input voltage			0.8		8.0	V	
VI	Input voltage		0	Vcc	0	VCC	V	
la	High-level output current	A port		-24		-32	mA	
ЮН		B port		-12		-12	IIIA	
1	Low lovel output ourrent	A port		48		64	mA	
lOL	Low-level output current	B port		12		12	l IIIA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V	
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V	
TA	Operating free-air temperature	-55	125	-40	85	°C		

NOTE 3: All unused inputs of the devices must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application note, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COL	IDITIONS	Т	T _A = 25°C SN54ABT162601 SN74AB		SN74ABT	162601	LINUT		
PAI	RAMETER	TEST CONDITIONS		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
	A nort	V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		
	A port	V 45V	I _{OH} = -24 mA	2			2				
\ \/ .		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2		V
VOH		V _{CC} = 4.5 V,	I _{OH} = -1 mA	3.35			3.3		3.35		V
	D	V _{CC} = 5 V,	I _{OH} = -1 mA	3.85			3.8		3.85		
	B port	\/ 4.5.\/	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1		
		V _{CC} = 4.5 V	I _{OH} = -12 mA	2.6					2.6		
	At	V 45V	I _{OL} = 48 mA			0.55		0.55			
VOL	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
	B port	V _{CC} = 4.5 V,	I _{OL} = 12 mA			0.8		0.8		0.8	
V _{hys}	•				100						mV
1.	Control inputs	V _{CC} = 0 to 5.5 V, V _I	= V _{CC} or GND			±1 ±1			±1		
l _l	A or B ports $V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ V _I = V _{CC} or GND		/,			±20		±20		±20	μА
lozpu	J	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V},$	OE = X			±50		±50**		±50	μΑ
IOZPE)	$V_{CC} = 2.1 \text{ V to 0},$ $V_{O} = 0.5 \text{ V to 2.7 V},$	OE = X			±50		±50**		±50	μΑ
lozн‡	:	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$				10		10		10	μΑ
lozL‡		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_{O} = 0.5 \text{ V}, \overline{OE} \ge 2 \text{ V}$	/, /			-10		-10		-10	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100*				±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO§	A port B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-50 -25	-100 -55	-180 -100	-50 -25	-180 -100	-50 -25	-180 -100	mA
		V _{CC} = 5.5 V,	Outputs high			3		3		3	
Icc	A or B ports	$I_{O} = 0$	Outputs low			36		36		36	mA
	, , , ,	$V_I = V_{CC}$ or GND	Outputs disabled			3		3		3	
ΔICC¶		V _{CC} = 5.5 V, One in Other inputs at V _{CC}	put at 3.4 V,			50		50		50	μΑ
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			9						pF
							<u>. </u>				

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

 $[\]dagger$ All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

SN54ABT162601, SN74ABT162601 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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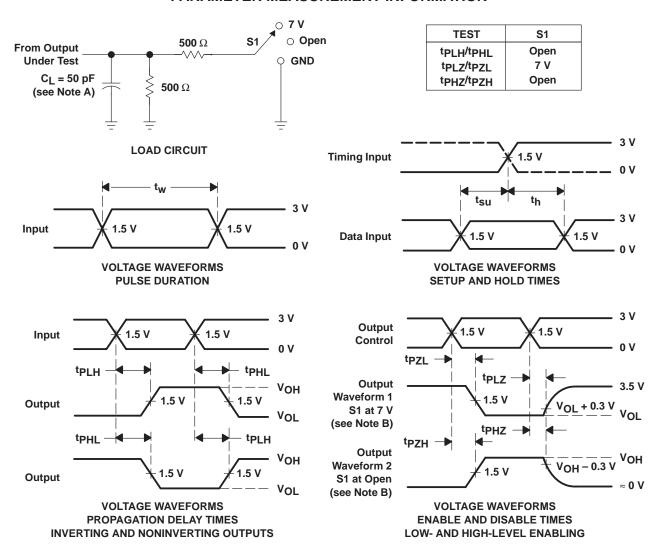
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(see Figure 1)

				SN54ABT162601		SN74ABT	UNIT	
				MIN	MAX	MIN	MAX	UNII
fclock	Clock frequency			0	150	0	150	MHz
	Pulse duration	LEAB or LEBA high				2.5		
t _W	Pulse duration	CLKAB or CLKBA high or low	3.3		3		ns	
		A before CLKAB↑ or B before CLKBA↑		4.8		4.3		
١.	Catum time	A before LEAB↓ or B before LEBA↓ CLK high CLK low	CLK high	2.5		2.5		
t _{su}	Setup time		1.2		1		ns	
		CLKEN before CLK↑		2.7		2.7		
		A after CLKAB↑ or B after CLKBA↑	fter CLKAB↑ or B after CLKBA↑			0		ns
t _h	Hold time	A after LEAB↓ or B after LEBA↓	2		0.5	·		
		CLKEN after CLK↑		0.5		0		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C SN54ABT162601 SN74ABT16		162601	1 UNIT						
	(INFO1)	(INPO1) (OU	(INPOT) (OUTPOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150		150		MHz		
^t PLH	A	В	1.5	2.8	4	1.5	5.1	1.5	4.8	ns		
t _{PHL}	A	Ь	2	3.7	5.2	2	6.1	2	5.7	115		
t _{PLH}	В	А	1	2.5	3.6	1	4.5	1	4	ns		
t _{PHL}	Ь	^	2	3.3	4.5	2	5.1	2	4.9	115		
^t PLH	LEBA	А	2	3.3	4.5	2	5.6	2	5	ns		
t _{PHL}	LEDA	A	2	3.6	4.7	2	5.4	2	5	115		
^t PLH	LEAB	В	2	3.4	4.8	2	6.1	2	5.6	ns		
^t PHL	LEAD	В	2	3.8	5.2	2	6.4	2	5.9	115		
^t PLH	CLKBA	А	1.5	3.1	4.7	1.5	5.4	1.5	5.3	ns		
^t PHL	CLNDA	^	1.5	3.1	4.3	1.5	5.2	1.5	5	115		
^t PLH	CLKAB	В	1.5	3.3	4.7	1.5	6	1.5	5.5	ns		
^t PHL	CLNAD	В	1.5	3.5	4.8	1.5	5.8	1.5	5.3	115		
^t PZH	OEBA	А	2	3.5	4.6	2	5.5	2	5.1	ns		
^t PZL	OEBA	^	2	3.7	4.7	2	5.8	2	5.4	115		
^t PZH	OFAR	В	2	3.8	5.3	1.5	6.6	2	6.1	ns		
^t PZL	OEAB		2	3.6	5.1	2	6.2	2	5.7	115		
^t PHZ	OEBA	А	2	3.6	5.4	1.4	6.6	2	6.2	ns		
t _{PLZ}			1.5	3.2	4.7	1.5	5.8	1.5	5.4	119		
^t PHZ	OEAB	В	2	3.4	4.8	1.4	5.6	2	5.4	ns		
^t PLZ	OLAB		1.5	3.2	4.5	1.5	5.7	1.5	5.2	115		

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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